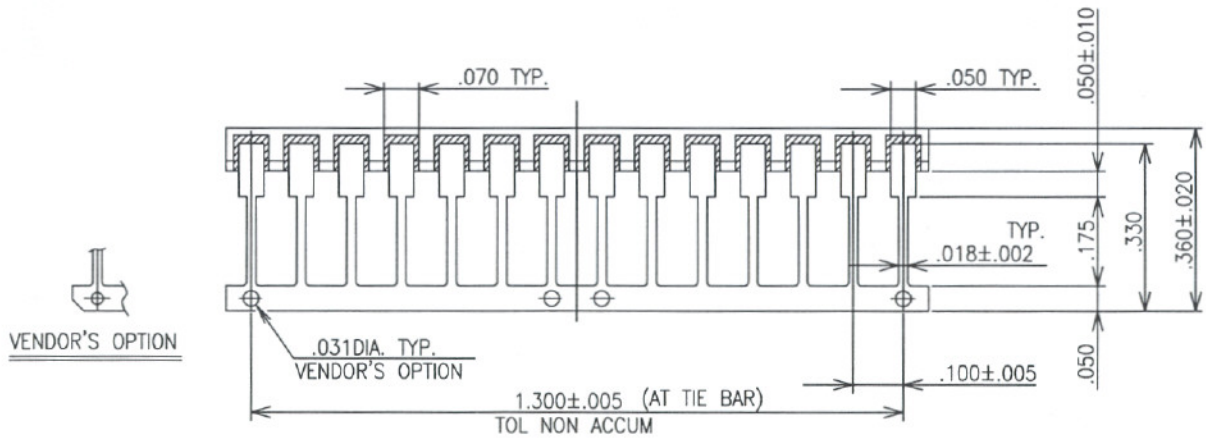
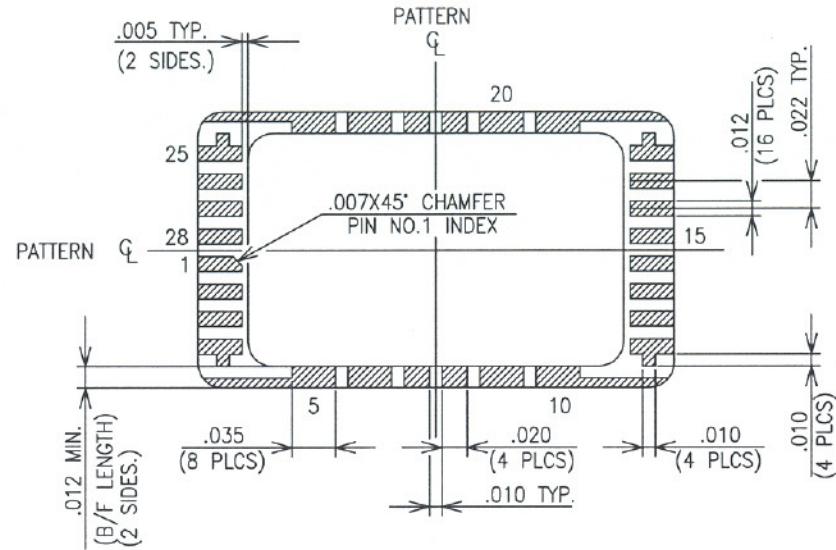


- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE : 0.40 OHMS MAX.



SB028AD025-1				S=0 D=0
DRAWN	CHECKED	APPROVED	DATE	
S.SH	H.S/S.F	T.A	JAN.13.'95	
DRAWING NO.				SHEET
KD-S95025				1/2

MODIFICATION	NAME	28 LEAD SIDE BRAZED PACKAGE			TOLERANCE	UNLESS OTHERWISE SPECIFIED	
	SCALE	4/1	MATERIAL	AS INDICATED	±.005	THIRD ANGLE PROJECTION	
CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN		



BONDING PATTERN

MODIFICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					28 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.SH	H.S/S.F	T.A	JAN.13.'95
					SCALE	MATERIAL	THIRD ANGLE PROJECTION			
					10/1					
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	DRAWING NO.				SHEET
						KD-S95025				2/2



KYOCERA CORPORATION
KYOTO JAPAN